

### Features

- Operating voltage: 2.4V~6.0V
- Very low standby current 0.5 $\mu$ A (Typ.)
- High signal-to-noise ratio
- High slew rate
- Output power 330mW at 10% THD+N into 8 $\Omega$
- Excellent power supply ripple rejection
- Low power consumption
- Wide temperature operating range
- Direct drive speaker
- Shutdown function
- 8-pin SOP package

### Applications

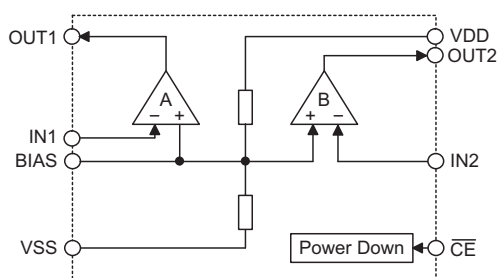
- CD ROM DVD player
- Notebook/Desktop PC
- Portable Audio Device
- Headphone Amplifier
- Microphone Pre-amplifier
- Discman/MP3

### General Description

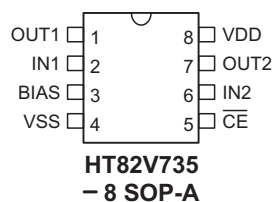
HT82V735 is a class AB stereo earphone driver designed for portable digital audio application. Pin assignments and application circuits are compatible with LM4880 which is suitable for effective low cost applications. The HT82V735 can deliver a maximum of 330mW

Output power to an 8 $\Omega$  load with less than 10% (THD+N) from a 5V power supply. The very low standby current in shutdown mode contributes to the reduction of power consumption of battery-powered equipments. It provides 8-SOP package.

### Block Diagram



### Pin Assignment



### Pin Description

Pin No.	Pin Name	I/O	Description
1	OUT1	O	Channel 1 output pin
2	IN1	I	Channel 1 Audio input
3	BIAS	I	Supports a voltage driver for internal bias
4	VSS	—	Negative power supply, ground
5	$\overline{CE}$	I	Power down mode when held high, I (power down) =1 $\mu$ A
6	IN2	I	Channel 2 Audio input
7	OUT2	O	Channel 2 output pin
8	VDD	—	Positive power supply

**Absolute Maximum Ratings**

Supply Voltage ..... $V_{SS}-0.3V$  to  $V_{SS}+6V$       Storage Temperature ..... $-50^{\circ}C$  to  $125^{\circ}C$   
 Input Voltage ..... $V_{SS}-0.3V$  to  $V_{DD}+0.3V$       Operating Temperature ..... $-20^{\circ}C$  to  $70^{\circ}C$

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

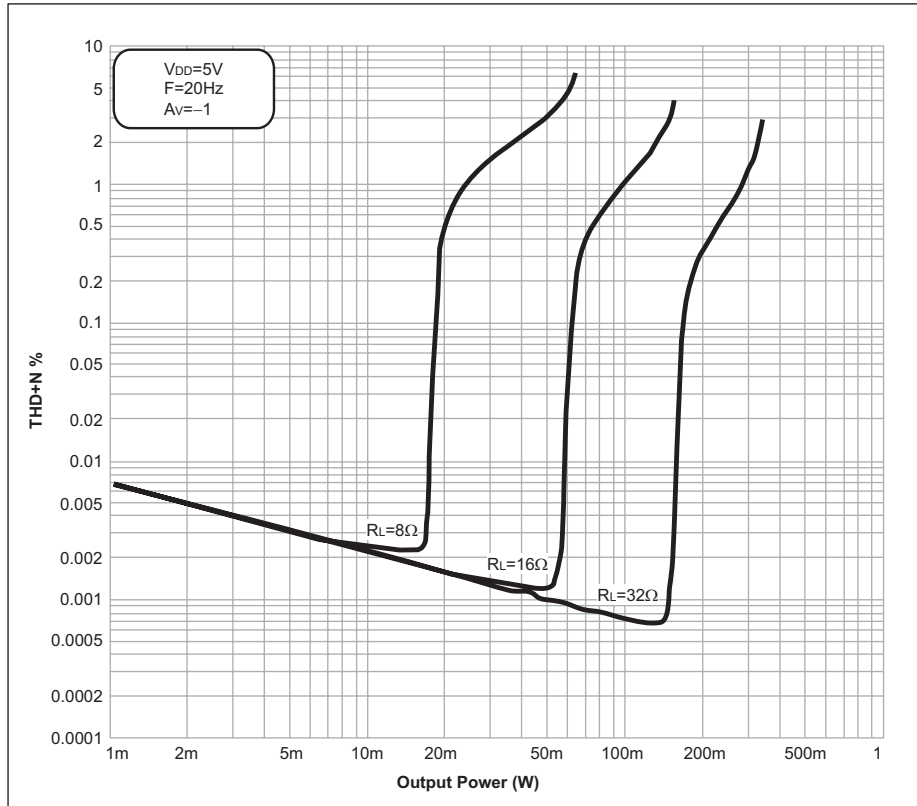
**Electrical Characteristics**
 $V_{SS}=0V$ ;  $f_i=1kHz$ ;  $R_L=32\Omega$ ;  $T_a=25^{\circ}C$ 

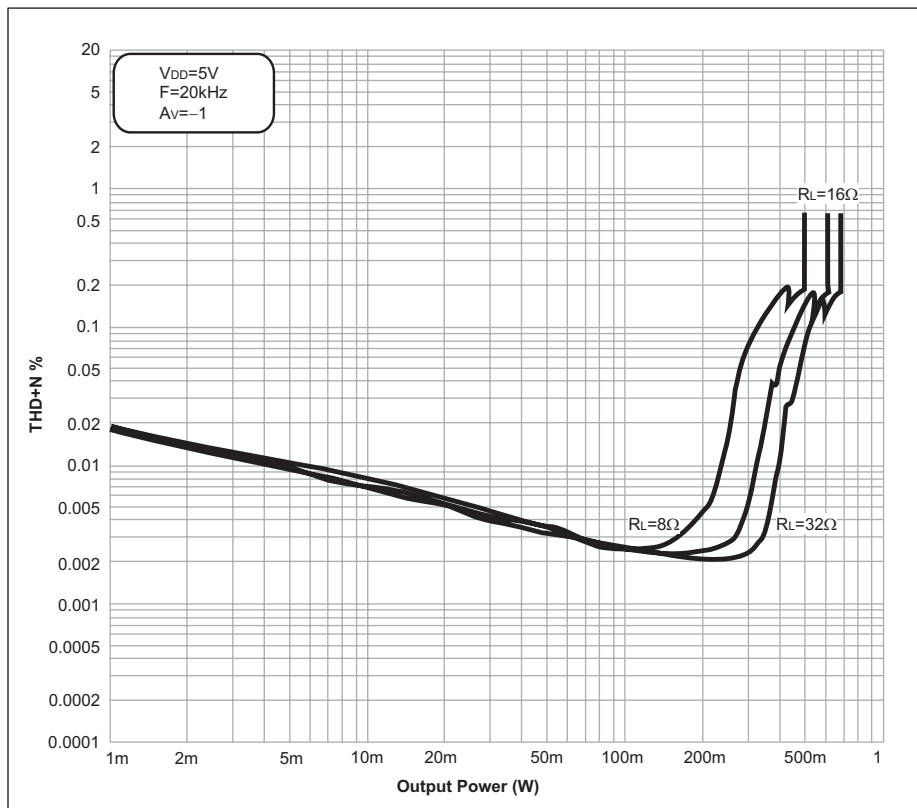
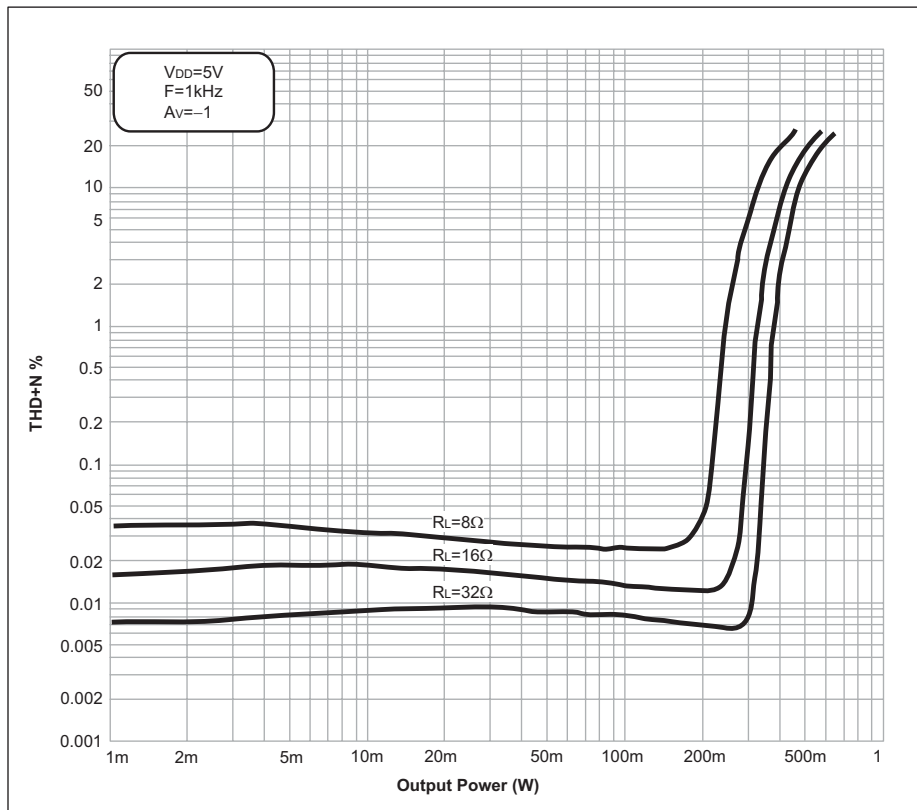
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		$V_{DD}$	Conditions				
<b>Supplies</b>							
$V_{DD}$	Supply Voltage	—	—	2.4	—	6	V
$I_{DD}$	Supply Current	5V	No load	—	10	—	mA
$I_{PD}$	Power-down Current	5V	—	—	1	—	$\mu A$
<b>D.C. Characteristics</b>							
$V_{I(OS)}$	Input Offset Voltage	5V	—	—	10	—	mV
$I_O$	Maximum Output Current	5V	(THD+N)/S<0.1%	—	62	—	mA
$R_O$	Output Resistance	5V	—	—	230	—	m $\Omega$
$V_O$	Output Voltage Swing	5V	$R_L=8\Omega$	0.66	—	3	V
			$R_L=16\Omega$	0.38	—	3.15	V
			$R_L=32\Omega$	0.18	—	3.29	V
PSRR	Power Supply Rejection Ratio	5V	$C_S=2.2\mu F$ , $V_{RIPPLE}=200V_{RMS}$ , $f=120Hz$	—	66	—	dB
$X_{TALK}$	Channel Separation	5V	$P_O=200mW$ , $R_L=8\Omega$ , $C_B=2.2\mu F$	—	85	—	dB
<b>A.C. Characteristics</b>							
(THD+N)/S	Total Harmonic Distortion Plus Noise to Signal Ratio	5V	$P_O=200mW$ , $R_L=8\Omega$ , $f=1kHz$	—	0.03	—	%
			$P_O=120mW$ , $R_L=16\Omega$ , $f=1kHz$	—	0.01	—	
			$P_O=75mW$ , $R_L=32\Omega$ , $f=1kHz$	—	0.01	—	
		3.3V	$P_O=30mW$ , $R_L=32\Omega$ , $f=1kHz$	—	0.01	—	
$P_O$	Output Power	5V	(THD+N)/S=0.1%, $f=1kHz$	—	—	—	mW
			$R_L=8\Omega$	—	240	—	
			$R_L=16\Omega$	—	160	—	
			$R_L=32\Omega$	—	90	—	
			(THD+N)/S=10%, $f=1kHz$	—	—	—	
			$R_L=8\Omega$	—	330	—	
			$R_L=16\Omega$	—	200	—	
$R_L=32\Omega$	—	110	—				

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
S/N	Signal to Noise Ratio	5V	V <sub>IN</sub> =1V <sub>RMS</sub> , R <sub>L</sub> =8Ω	—	92	—	dB
SR	Slew Rate	5V	—	—	3	—	V/μs
ATT	Power-down Attenuation	5V	1kHz, 0dB	—	70	—	dB

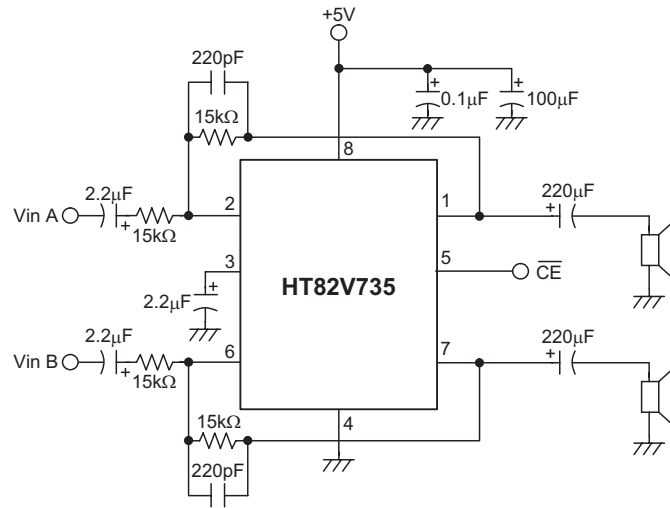
### Typical Performance Characteristics

#### THD+N vs. Output Power



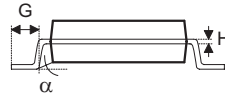
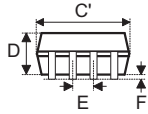
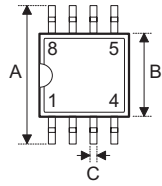


Application Circuits



**Package Information**

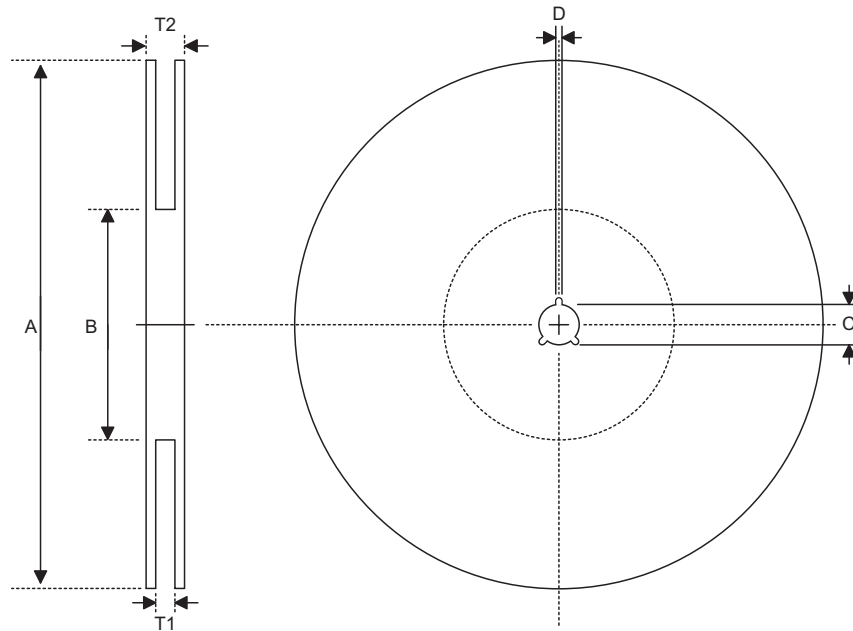
**8-pin SOP (150mil) Outline Dimensions**



Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	228	—	244
B	149	—	157
C	14	—	20
C'	189	—	197
D	53	—	69
E	—	50	—
F	4	—	10
G	22	—	28
H	4	—	12
$\alpha$	0°	—	10°

**Product Tape and Reel Specifications**

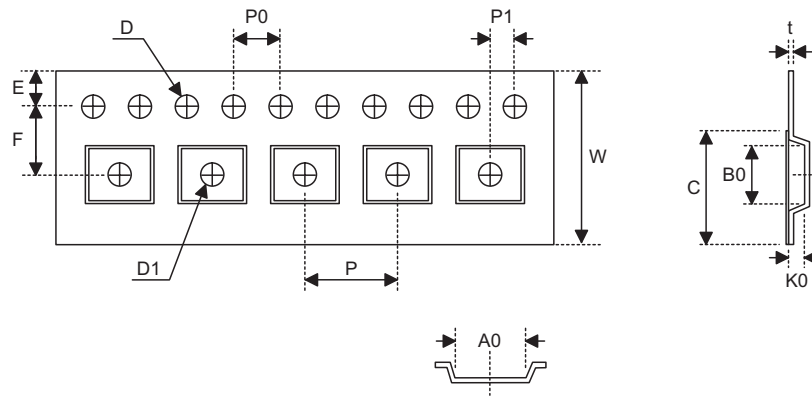
**Reel Dimensions**



SOP 8N

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330±1.0
B	Reel Inner Diameter	62±1.5
C	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	12.8+0.3 -0.2
T2	Reel Thickness	18.2±0.2

**Carrier Tape Dimensions**



**SOP 8N**

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
P	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
B0	Cavity Width	5.20±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.3±0.05
C	Cover Tape Width	9.3



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